

AOK53S60-VB Datasheet

N-Channel 600V (D-S) Super Junction Power MOSFET

PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	600)
R _{DS(on)} at 25 °C (Ω)	V _{GS} = 10 V	0.060

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)

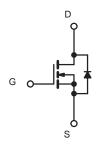
APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- - High-intensity discharge (HID)
 - Fluorescent ballast lighting









N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	600	V
Gate-Source Voltage			V_{GS}	± 30	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Continuous Proin Current (T. – 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I _D	47	
Continuous Drain Current (T _J = 150 °C)		T _C = 100 °C		29	Α
Pulsed Drain Current ^a			I _{DM}	140	
Linear Derating Factor				1.67	W/°C
Single Pulse Avalanche Energy b			E _{AS}	850	mJ
Maximum Power Dissipation			P_{D}	510	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope	T _J = 125 °C		dV/dt	50	1//20
everse Diode dV/dt d			uv/di	15	- V/ns
Soldering Recommendations (Peak Temperature) ^c	for	10 s		260	°C

- a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD}=100$ V, starting $T_J=25$ °C, L = 30mH, $R_g=25$ Ω , $I_{AS}=24$ A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C.



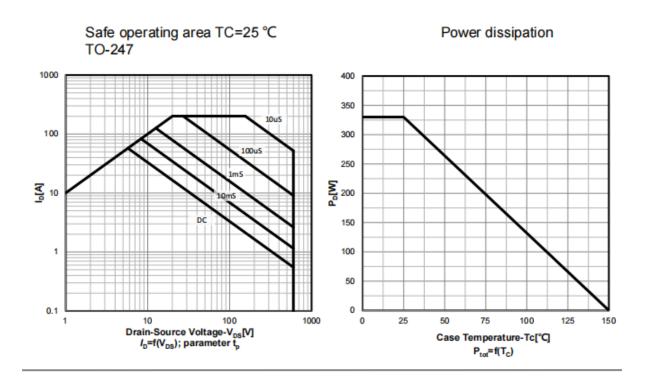
THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.38	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•					•
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 1 mA		600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 1 mA		0.70	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.5	-	4.5	V
			V _{GS} = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V	-	-	± 1	μΑ
		V _{DS} =	= 600V, V _{GS} = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V, T _J = 125 °C		-	100	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D =16A	-	0.060	-	Ω
Forward Transconductance	9fs	V _{DS}	s = 30 V, I _D = 16 A	-	5.6	-	S
Dynamic					•		
Input Capacitance	C _{iss}		V _{GS} = 0 V,	-	4900	-	
Output Capacitance	Coss	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		-	330	-	pF
Reverse Transfer Capacitance	C _{rss}			-	4	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	- V _{DS} = 0 V to 520 V, V _{GS} = 0 V		-	63	-	
Effective Output Capacitance, Time Related ^b	$C_{o(tr)}$			-	213	-	
Total Gate Charge	Qg			-	370	-	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 \text{ V}$	$I_D = 20 \text{ A}, V_{DS} = 520 \text{ V}$	-	3 9	-	nC
Gate-Drain Charge	Q_{gd}			ı	4 7	-	
Turn-On Delay Time	$t_{d(on)}$			1	18	25	
Rise Time	t _r	$V_{DD} = 520 \text{ V}, I_D = 20\text{A},$		1	24	55	ns
Turn-Off Delay Time	t _{d(off)}			ı	8 0	-	113
Fall Time	t _f	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		-	1 2	-	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	0.8	-	Ω
Drain-Source Body Diode Characteristic	S						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	47	
Pulsed Diode Forward Current	I _{SM}			-	-	140	- A
Diode Forward Voltage	V _{SD}	T _J = 25 °	C, I _S = 8 A, V _{GS} = 0 V	-	-	1.5	V
Reverse Recovery Time	t _{rr}	-		-	520	-	ns
Reverse Recovery Charge	Q _{rr}	T _J = 25 °C, I _F = I _S = 8 A, dl/dt = 100 A/ μ s, V _R = 400 V		-	5.8	-	μC
Reverse Recovery Current	I _{RBM}				4 5	_	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .





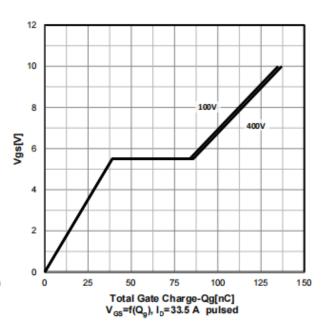
Typ. output characteristics T_i =25 $^{\circ}$ C Transfer characteristics 300 300 25°C . I_D, Drain Current [A] Drain Current [A] 200 150°C -0 0 5 10 15 20 0 2 10 12 V_{GS}, Gate-Source Voltage [V] V_{DS}, Drain to Source Voltage [V]



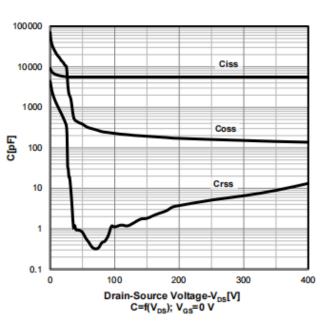
Typ. drain-source on-state resistance

80
70
60
60
40
30
20
0 15 30 45 60 75 90
Drain-Source Current-I_D[A]
R_{DS}(on)=f(I_D); parameter:V_{GS}

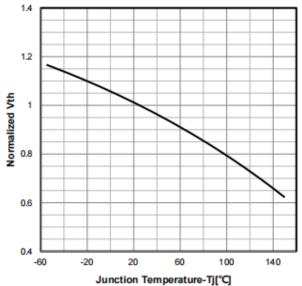
Typ. gate charge characteristics



Typ. capacitances



Normalized $V_{\text{GS(th)}}$ characteristics

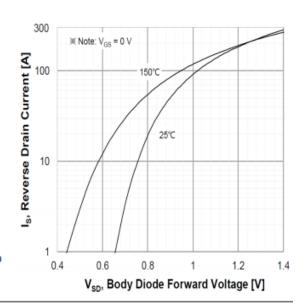




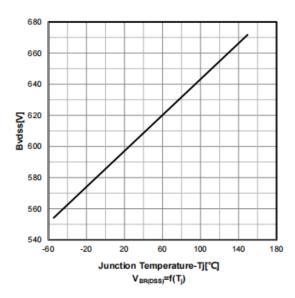
On-resistance vs temperature

120 100 80 40 40 40 Typ 40 Junction Temperature-Tj[°C] R_{DS}(on)=f(T_j); I_D=33.5 A; V_{GS}=10 V

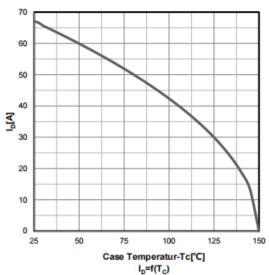
Forward characteristics of reverse diode



Drain-source breakdown voltage



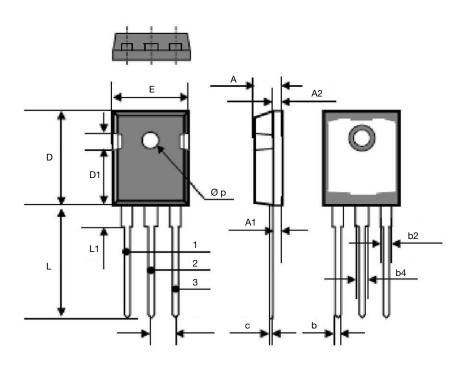
Drain current vs temperature



服务热线:400-655-8788 5



TO-247



DIM.	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
А	4.70	5.31	0.185	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b2	1.65	2.41	0.065	0.095	
b4	2.59	3.43	0.102	0.135	
С	0.61	BSC	0.024 BSC		
D	20.80	21.46	0.819	0.845	
D1	3.68	5.49	0.145	0.216	
(e)	5.46	BSC	0.215	BSC	
E	15.49	16.26	0.610	0.640	
L	19.81	20.32	0.780	0.800	
L1	4.06	4.50	0.160	0.177	
Øр	3.51	3.66	0.138	0.144	



Disclaimer

All products due to improve reliability, function or design or for other reasons, product specifications and data are subject to change without notice.

Taiwan VBsemi Electronics Co., Ltd., branches, agents, employees, and all persons acting on its or their representatives (collectively, the "Taiwan VBsemi"), assumes no responsibility for any errors, inaccuracies or incomplete data contained in the table or any other any disclosure of any information related to the product.(www.VBsemi.com)

Taiwan VBsemi makes no guarantee, representation or warranty on the product for any particular purpose of any goods or continuous production. To the maximum extent permitted by applicable law on Taiwan VBsemi relinquished: (1) any application and all liability arising out of or use of any products; (2) any and all liability, including but not limited to special, consequential damages or incidental; (3) any and all implied warranties, including a particular purpose, non-infringement and merchantability guarantee.

Statement on certain types of applications are based on knowledge of the product is often used in a typical application of the general product VBsemi Taiwan demand that the Taiwan VBsemi of. Statement on whether the product is suitable for a particular application is non-binding. It is the customer's responsibility to verify specific product features in the products described in the specification is appropriate for use in a particular application. Parameter data sheets and technical specifications can be provided may vary depending on the application and performance over time. All operating parameters, including typical parameters must be made by customer's technical experts validated for each customer application. Product specifications do not expand or modify Taiwan VBsemi purchasing terms and conditions, including but not limited to warranty herein.

Unless expressly stated in writing, Taiwan VBsemi products are not intended for use in medical, life saving, or life sustaining applications or any other application. Wherein VBsemi product failure could lead to personal injury or death, use or sale of products used in Taiwan VBsemi such applications using client did not express their own risk. Contact your authorized Taiwan VBsemi people who are related to product design applications and other terms and conditions in writing.

The information provided in this document and the company's products without a license, express or implied, by estoppel or otherwise, to any intellectual property rights granted to the VBsemi act or document. Product names and trademarks referred to herein are trademarks of their respective representatives will be all.

Material Category Policy

Taiwan VBsemi Electronics Co., Ltd., hereby certify that all of the products are determined to be RoHS compliant and meets the definition of restrictions under Directive of the European Parliament 2011/65 / EU, 2011 Nian. 6. 8 Ri Yue restrict the use of certain hazardous substances in electrical and electronic equipment (EEE) - modification, unless otherwise specified as inconsistent.(www.VBsemi.com)

Please note that some documents may still refer to Taiwan VBsemi RoHS Directive 2002/95 / EC. We confirm that all products identified as consistent with the Directive 2002/95 / EC European Directive 2011/65 /.

Taiwan VBsemi Electronics Co., Ltd. hereby certify that all of its products comply identified as halogen-free halogen-free standards required by the JEDEC JS709A. Please note that some Taiwanese VBsemi documents still refer to the definition of IEC 61249-2-21, and we are sure that all products conform to confirm compliance with IEC 61249-2-21 standard level JS709A.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by VBsemi Elec manufacturer:

Other Similar products are found below:

IRFD120 IRFY240C JANTX2N5237 2SK2267(Q) BUK455-60A/B MIC4420CM-TR VN1206L NDP4060 SI4482DY

IPS70R2K0CEAKMA1 SQD23N06-31L-GE3 TK16J60W,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 EFC2J004NUZTDG

DMN1053UCP4-7 SQJ469EP-T1-GE3 NTE2384 DMC2700UDMQ-7 DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR

DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 IRF40H233XTMA1 STU5N65M6

DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y
TP MCQ7328-TP NTMC083NP10M5L NVMFS2D3P04M8LT1G BXP7N65D BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L

BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13